12.27.06

01-05-2007

103357036

FORM PTO-1595
1-31-92

ET

U.S. Department of Commerce
Patent and Trademark Office
Attorney Docket No. 09415.0010
Attorney Customer Number: 22,852

To the Honorable Commissioner
Please record the attached original documents or copy thereof.

ATTN. BOX ASSIGNMENTS RECORDATION SERVICES

1. Name of conveying party:

Han-Choon LEE

Additional name of conveying party attached? ☐ Yes ☒ No

2. Name and address of receiving party:

Name: **Dongbu Electronics Co., Ltd.**

Internal Address: *891-10 Daechi-dong, Gangnam-gu*
Seoul, Korea

Street Address:

City:

State:

Zip Code:

113010 U.S. PTO
11/645533
122706

Additional name & Address attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other:

Execution Date: **November 30, 2006**

4. Application number or patent number: If this document is being filed together with a new application, the execution date of the application: **November 30, 2006**

A. Patent Application Number:

B. Patent Number:

12/28/2006 FMETEKI1 00000062 11645533
04 FC:8021 40.00 OP

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

Street Address: 901 New York Avenue, NW

City: Washington, D.C.

State: Zip: 20001-4413

6. Total number of applications and registrations involved: 1

7. Total fee (37 CFR 3.41): $40

☒ Enclosed (Please charge deficiency to deposit account)

☐ Authorized to be charged to deposit account

8. Deposit Account No.: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman
Reg. No. 25,961

Signature

December 27, 2006
Date

Total number of pages including cover sheet, attachments and documents: 2

SOLE/JOINT INVENTION
(U.S. Rights Only)
Attorney Docket No. 09415.0010

ASSIGNMENT

WHEREAS I/We, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

METHOD FOR FABRICATING A THIN FILM AND METAL LINE OF A SEMICONDUCTOR DEVICE

for which I/WE executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on , 20 (Application No.); and

WHEREAS, Dongbu Electronics Co., Ltd.
a corporation of Republic of Korea

whose post office address is 891-10, Daechi-dong, Gangnam-gu, Seoul, Korea

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as Assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY further covenant and agree that We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. , filed) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, We have hereunto set our hands.

1. FULL NAME OF SOLE OR FIRST ASSIGNOR Han-Choon LEE	ASSIGNOR'S SIGNATURE	DATE 2006. 11. 30
ADDRESS 891-10, Daechi-dong, Gangnam-gu, Seoul, Korea		CITIZENSHIP Republic of Korea